



### **Product Summary**

| BV <sub>DSS</sub> | R <sub>DS(ON)</sub> Max        | I <sub>D</sub> Max<br>T <sub>A</sub> = +25°C |
|-------------------|--------------------------------|--|
| 4017              | 11.5mΩ @ V <sub>GS</sub> = 10V | 11.6A  |
| 40V               | 18mΩ @ V <sub>GS</sub> = 4.5V  | 9.3A   |

## Description

This MOSFET is designed to meet the stringent requirements of automotive applications. It is qualified to AEC-Q101, supported by a PPAP and is ideal for use in:

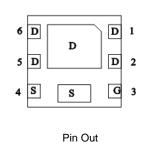
- Power Management Functions
- DC-DC Converters
- Backlighting

#### Features

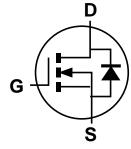
- Rated to +175°C Ideal for High Ambient Temperature Environments
- 100% Unclamped Inductive Switching Ensures More Reliable and Robust End Application
- Low R<sub>DS(ON)</sub> Ensures On State Losses Are Minimized
- 0.6mm Profile Ideal for Low Profile Applications
- PCB Footprint of 4mm<sup>2</sup>
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

### **Mechanical Data**

- Case: U-DFN2020-6 (SWP) (Type F)
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.0065 grams (Approximate)



Bottom View



Internal Schematic

U-DFN2020-6 (SWP) (Type F)

Top View

Bottom View

# Ordering Information (Note 5)

| Part Number       | Case                       | Quantity Per Reel |
|-------------------|----------------------------|-------------------|
| DMTH4008LFDFWQ-7  | U-DFN2020-6 (SWP) (Type F) | 3,000             |
| DMTH4008LFDFWQ-13 | U-DFN2020-6 (SWP) (Type F) | 10,000            |

1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.

 See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

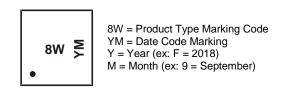
3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.

5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/.

# **Marking Information**

Notes:



| Date Code Key |     |     |      |     |     |      |     |     |      |      |     |      |
|---------------|-----|-----|------|-----|-----|------|-----|-----|------|------|-----|------|
| Year          | 201 | 7   | 2018 | 201 | 9   | 2020 | 202 | 1   | 2022 | 2023 | 3   | 2024 |
| Code          | E   |     | F    | G   |     | Н    |     |     | J    | K    |     | L    |
| Month         | Jan | Feb | Mar  | Apr | Мау | Jun  | Jul | Aug | Sep  | Oct  | Nov | Dec  |
| Code          | 1   | 2   | 3    | 4   | 5   | 6    | 7   | 8   | 9    | 0    | N   | D    |

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# Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

| Characteristic  | Symbol           | Value           | Unit |   |
|---|------------------|-----------------|------|---|
| Drain-Source Voltage  | V <sub>DSS</sub> | 40              | V    |   |
| Gate-Source Voltage   | V <sub>GSS</sub> | ±20             | V    |   |
| Continuous Drain Current (Note 7) $V_{GS}$ = 10V                | ID               | 11.6<br>8.2     | А    |   |
| Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)              |                  | I <sub>DM</sub> | 80   | A |
| Continuous Source-Drain Diode Current (Note 7)                  |                  | I <sub>S</sub>  | 2.55 | A |
| Pulsed Source-Drain Diode Current (10µs Pulse, Duty Cycle = 1%) |                  | I <sub>SM</sub> | 80   | А |
| Avalanche Current, L = 0.3mH (Note 8)                           | IAS              | 14.7            | A    |   |
| Avalanche Energy, L = 0.3mH (Note 8)                            | E <sub>AS</sub>  | 32.4            | mJ   |   |

### **Thermal Characteristics**

| Characteristic                                   |                        | Symbol                            | Value       | Unit |
|--|------------------------|-----------------------------------|-------------|------|
| Total Power Dissipation (Note 6)                 | T <sub>A</sub> = +25°C | PD                                | 0.99        | W    |
| Thermal Resistance, Junction to Ambient (Note 6) | Steady State           | R <sub>0JA</sub>                  | 153         | °C/W |
| Total Power Dissipation (Note 7)                 | T <sub>A</sub> = +25°C | PD                                | 2.35        | W    |
| Thermal Resistance, Junction to Ambient (Note 7) | Steady State           | R <sub>0JA</sub>                  | 64.5        | °C/W |
| Thermal Resistance, Junction to Case (Note 7)    | T <sub>C</sub> = +25°C | R <sub>θJC</sub>                  | 14.8        | °C/W |
| Operating and Storage Temperature Range          |                        | T <sub>J</sub> , T <sub>STG</sub> | -55 to +175 | °C   |

# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

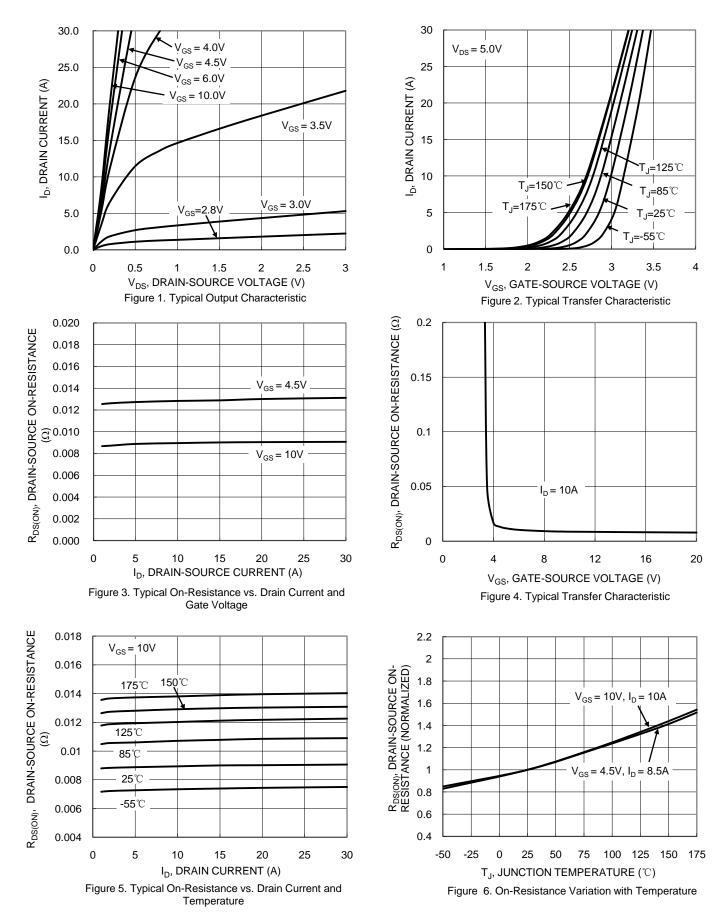
| Characteristic                             | Symbol              | Min | Тур  | Max  | Unit  | Test Condition                           |  |
|--|---------------------|-----|------|------|-------|--|--|
| OFF CHARACTERISTICS (Note 9)               |                     |     |      |      |       |  |  |
| Drain-Source Breakdown Voltage             | BV <sub>DSS</sub>   | 40  | _    | —    | V     | $V_{GS} = 0V, I_D = 250 \mu A$           |  |
| Zero Gate Voltage Drain Current            | IDSS                | —   | _    | 1    | μA    | $V_{DS} = 32V, V_{GS} = 0V$              |  |
| Gate-Source Leakage                        | I <sub>GSS</sub>    | —   |      | ±100 | nA    | $V_{GS} = \pm 20V, V_{DS} = 0V$          |  |
| ON CHARACTERISTICS (Note 9)                |                     |     |      |      |       |  |  |
| Gate Threshold Voltage                     | V <sub>GS(TH)</sub> | 1   | 1.7  | 3    | V     | $V_{DS} = V_{GS}, I_D = 250 \mu A$       |  |
| Static Drain-Source On-Resistance          | Deserve             |     | 9.1  | 11.5 | mΩ    | $V_{GS} = 10V, I_D = 10A$                |  |
|  | R <sub>DS(ON)</sub> | _   | 12.9 | 18   | 11152 | $V_{GS} = 4.5V, I_D = 8.5A$              |  |
| Diode Forward Voltage                      | V <sub>SD</sub>     | _   | 0.8  | 1.0  | V     | $V_{GS} = 0V, I_{S} = 10A$               |  |
| DYNAMIC CHARACTERISTICS (Note 10)          |                     |     |      |      |       |  |  |
| Input Capacitance                          | Ciss                | —   | 1030 | —    |       | $V_{DS} = 20V, V_{GS} = 0V,$<br>f = 1MHz |  |
| Output Capacitance                         | Coss                | _   | 324  | —    | pF    |  |  |
| Reverse Transfer Capacitance               | C <sub>rss</sub>    | —   | 27   | —    |       | $I = I W I I \Sigma$                     |  |
| Gate Resistance                            | Rg                  | _   | 1.82 | —    | Ω     | $V_{DS} = 0V, V_{GS} = 0V, f = 1MHz$     |  |
| Total Gate Charge (V <sub>GS</sub> = 4.5V) | Qg                  | _   | 6.8  | —    |       |  |  |
| Total Gate Charge (V <sub>GS</sub> = 10V)  | Qg                  | _   | 14.2 | —    | nC    |  |  |
| Gate-Source Charge                         | Q <sub>gs</sub>     | _   | 2.0  | —    | nc    | $V_{DD} = 20V, I_D = 10A$                |  |
| Gate-Drain Charge                          | Q <sub>gd</sub>     | _   | 2.7  | —    |       |  |  |
| Turn-On Delay Time                         | t <sub>D(ON)</sub>  | _   | 3.1  | —    |       |  |  |
| Turn-On Rise Time                          | t <sub>R</sub>      | _   | 3.1  | _    |       | $V_{DD} = 20V, V_{GS} = 10V,$            |  |
| Turn-Off Delay Time                        | t <sub>D(OFF)</sub> | _   | 14.2 | —    | ns    | $R_g = 6\Omega, I_D = 10A$               |  |
| Turn-Off Fall Time                         | t <sub>F</sub>      | _   | 5.8  | _    | 1     | -  |  |
| Reverse Recovery Time                      | t <sub>RR</sub>     | _   | 19.6 | —    | ns    |  |  |
| Reverse Recovery Charge                    | Q <sub>RR</sub>     | —   | 8.2  | —    | nC    | $I_F = 10A$ , di/dt = 100A/µs            |  |

Notes: 6. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.

6. Device mounted on FR-4 substrate PC board, 202 copper, with flinch recommended parts of the substrate PC board, 202 copper, with flinch square copper plate. 8.  $I_{AS}$  and  $E_{AS}$  ratings are based on low frequency and duty cycles to keep  $T_J = + 25^{\circ}$ C. 9. Short duration pulse test used to minimize self-heating effect. 10. Guaranteed by design. Not subject to product testing.



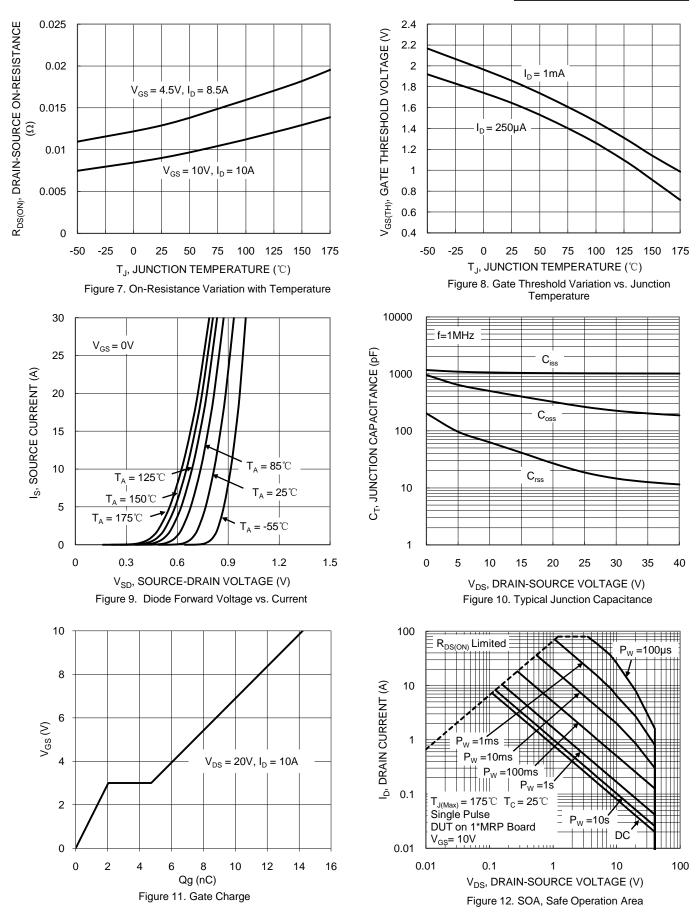
# DMTH4008LFDFWQ



DMTH4008LFDFWQ Datasheet number: DS39771 Rev. 3 - 2



# DMTH4008LFDFWQ





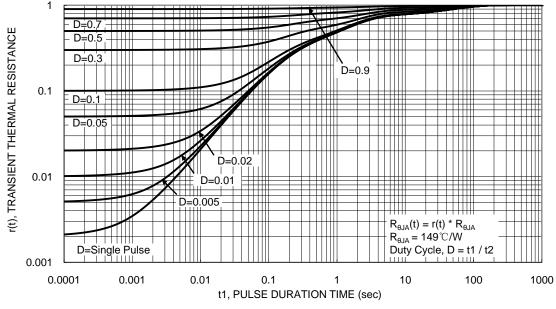
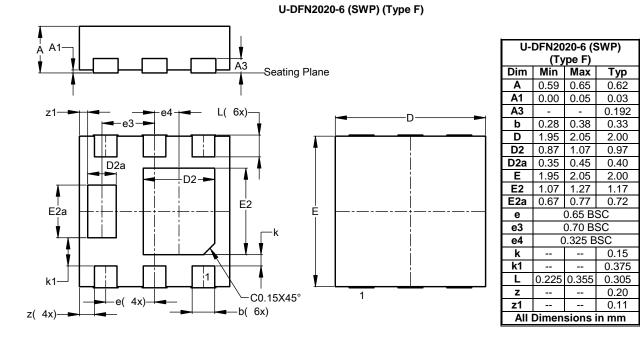


Figure 13. Transient Thermal Resistance



# **Package Outline Dimensions**

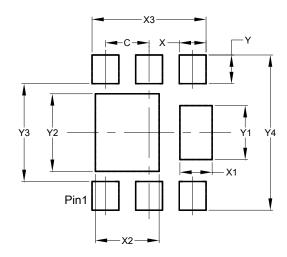
Please see http://www.diodes.com/package-outlines.html for the latest version.



# **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2020-6 (SWP) (Type F)



| Dimensions | Value   |  |  |  |  |
|------------|---------|--|--|--|--|
| Dimensions | (in mm) |  |  |  |  |
| С          | 0.650   |  |  |  |  |
| Х          | 0.400   |  |  |  |  |
| X1         | 0.480   |  |  |  |  |
| X2         | 0.950   |  |  |  |  |
| X3         | 1.700   |  |  |  |  |
| Y          | 0.425   |  |  |  |  |
| Y1         | 0.800   |  |  |  |  |
| Y2         | 1.150   |  |  |  |  |
| Y3         | 1.450   |  |  |  |  |
| Y4         | 2.300   |  |  |  |  |



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